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3510-DS-P

DEPARTMENT OF COMMERCE

Foreign-Trade Zones Board

[B-124-2026]

Foreign-Trade Zone (FTZ) 106, Notification of Proposed Production Activity; Hitachi Vantara Manufacturing; (Enterprise Datacenter Disk Storage System Hardware); Norman, Oklahoma

Hitachi Vantara Manufacturing submitted a notification of proposed production activity to the FTZ Board (the Board) for its facility in Norman, Oklahoma, within FTZ 106. The notification conforming to the requirements of the Board's regulations (15 CFR 400.22) was received on September 16, 2026.

Pursuant to 15 CFR 400.14(b), FTZ production activity would be limited to the specific foreign-status material(s)/component(s) and specific finished product(s) described in the submitted notification (summarized below) and subsequently authorized by the Board. The benefits that may stem from conducting production activity under FTZ procedures are explained in the background section of the Board's website – accessible via www.trade.gov/ftz.

The proposed finished products include: various fans (microprocessor cooling; accelerator); various bezels (flash model; front cover); various drives (hard disk; flash module; solid state); various boards (channel; front end communication controller; disk; processor blade); various boxes (channel board; internal components drive bay; flash drive); various chassis (controller; computer); various adapters (host; back end communication disk); service processors; cache memory chips; various kits (earthquake resistant rail attachment; operation panel); brackets; computer chassis rack rails; various modules (compression accelerator; optional encryption); computer controllers; various panels (name plate décor; filler); key kit brackets; computer chassis racks;

controller slot safety covers; storage bridge bays; RK42 rack side covers; maintenance PC trays; power control units; nickel-metal hydride (NiMH) batteries; fiber channel blades; network connection points; various cables (high performance data; optical; peripheral component interconnect express; copper; ethernet; local area network; quad small form factor pluggable); various transceivers (quad small form factor pluggable; small form factor pluggable); and, temporary data cache flash memory chips (duty rate ranges from duty-free to 3.4%).

The proposed foreign-status materials/components include: various ribbon (thermal transfer; label); various labels (blank polyester film; self-adhesive polyester film; printed barcode); polyethylene bags; various plastic components (connector covers; insulation sheets; name plates; cable ties; tags; clamps); textile gaskets; longhead bolts of iron or steel; various nickel components (bind screws; bolts; screws; nuts); various steel components (not threaded ball studs; longhead bolts; rail springs); stainless steel nuts; springs of iron or steel; various fans (microprocessor cooling; axial); sheet metal boxes for fans; various drives (hard magnetic disk; flash memory; solid state); various units (adapter; computer controller; computer bezel faceplate; central processing); mix adaptor instrument connectors; various modules (dual in-line memory; optional encryption); accelerators with fans; air guides; ball catches; various sheet metal components (base plates; computer cage security enclosures; computer outer shell cannisters; disc adaptor face plate covers; controller fan latch plates); brackets; cable ducts; chamfer angle brackets; various boards (channel; light emitting device; printed circuit); computer chassis; flexible polyurethane foam cushions; drive boxes; dummy spacers; flanges; gaskets; heat sinks; polyphenylene insulation; key plates; mylar sheets; indicator panels; polycarbonate light pipes; printed circuit board assemblies; rack rails; sheet metal fillers; shield fingers; wind shields; AC/DC switching power supplies; chip inductors; chassis with printed circuit board assemblies; various batteries

(NiMH; lithium); network connection points; various switches (ethernet; interconnect; push; slide); optical transceivers; printed circuit board assemblies with local area network controllers; various memory chips (temporary data cache flash; dynamic read write random access; non-volatile flash storage; electrically erasable programmable read only); chip capacitors; chip resistors; computer connector ports; central processing unit sockets; backplanes; various covers (quad small form factor pluggable; front frame); socket carriers; power connector housings; transistors; switch regulators; piezoelectric quartz crystals; computer controllers; complex programmable logic devices; field programmable gate arrays; system-on-chip processors; oscillators; flash memory drive; power management integrated circuits; various cables (copper telecommunication; flexible flat; optical fiber); insulated wires; insulation sheets; and, polymer clad optical fiber (duty rate ranges from duty-free to 7.9%).

The request indicates that certain materials/components are subject to duties under section 232 of the Trade Expansion Act of 1962, or section 301 of the Trade Act of 1974, depending on the country of origin. The applicable section 232, and section 301 decisions require subject merchandise to be admitted to FTZs in privileged foreign status as described in 19 CFR 146.41.

Public comment is invited from interested parties. Submissions shall be addressed to the Board's Executive Secretary and sent to: ftz@trade.gov. The closing period for their receipt is **[INSERT DATE 40 DAYS AFTER DATE OF PUBLICATION IN THE FEDERAL REGISTER]**.

A copy of the notification will be available for public inspection in the "Online FTZ Information System" section of the Board's website.

For further information, contact Juanita Chen at juanita.chen@trade.gov.

Dated: September 23, 2026.

Colin Agostisi,
Executive Secretary.

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